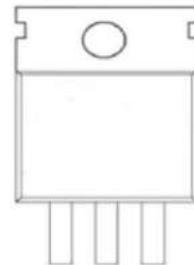
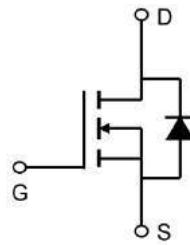


Description

The 120N09 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V.

This device is suitable for use as a Battery protection or in other Switching application.



General Features

$V_{DS} = 95V$ $I_D = 120A$

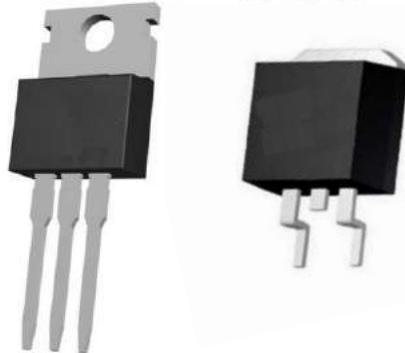
$R_{DS(ON)} < 7.0m\Omega$ $V_{GS} = 10V$ (Type: 5.8m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings (TC=25°C unless otherwise noted)

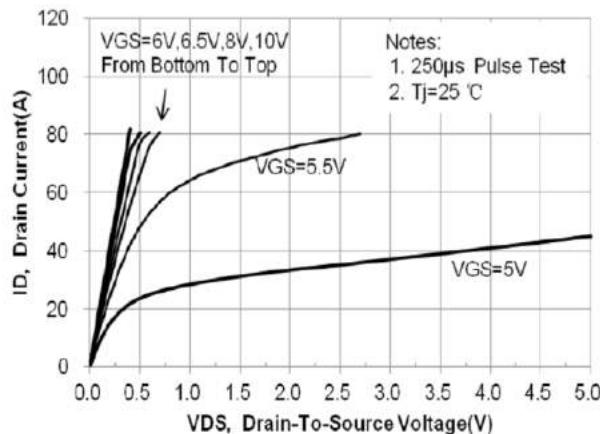
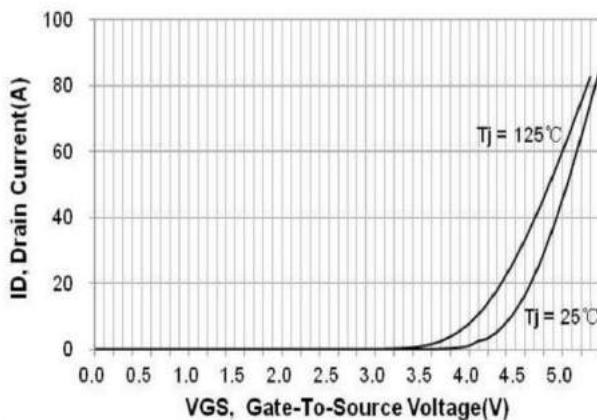
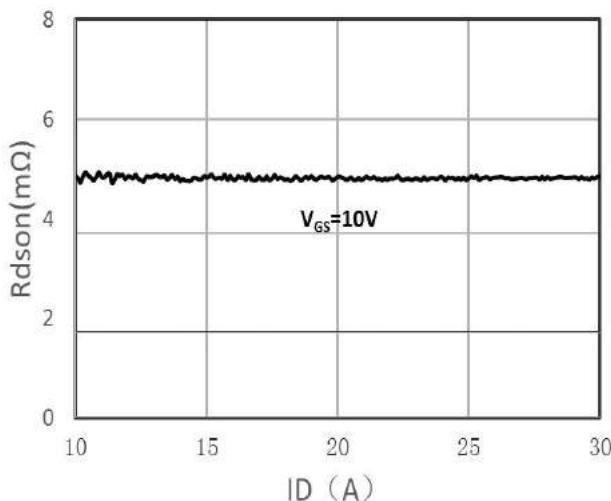
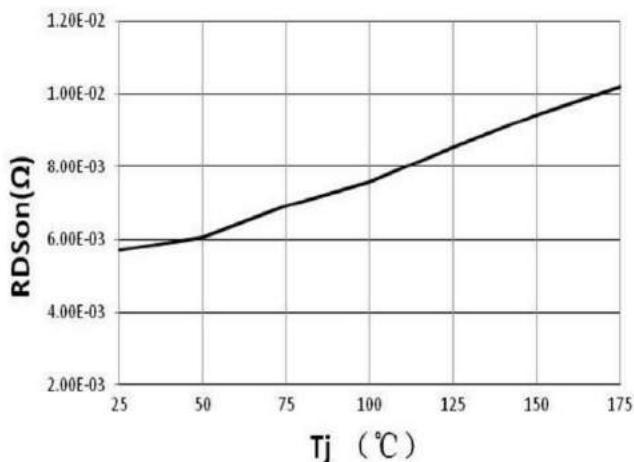
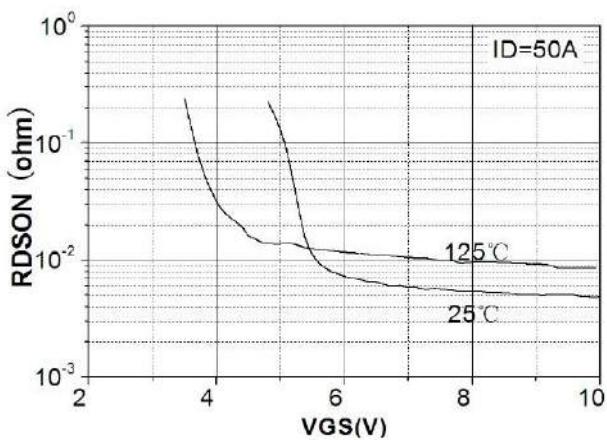
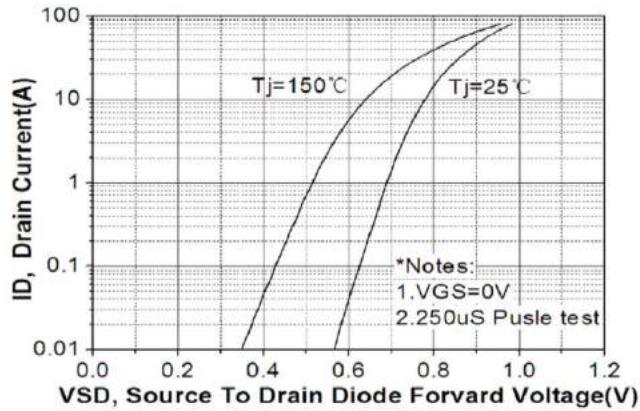
Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	95	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@TC=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	120	A
$I_D@TC=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	87	A
IDM	Pulsed Drain Current	480	A
EAS	Single Pulse Avalanche Energy	576	mJ
IAS	Avalanche Current	36.4	A
$PD@TC=25^\circ C$	Total Power Dissipation	17	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	0.70	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case	60	°C/W

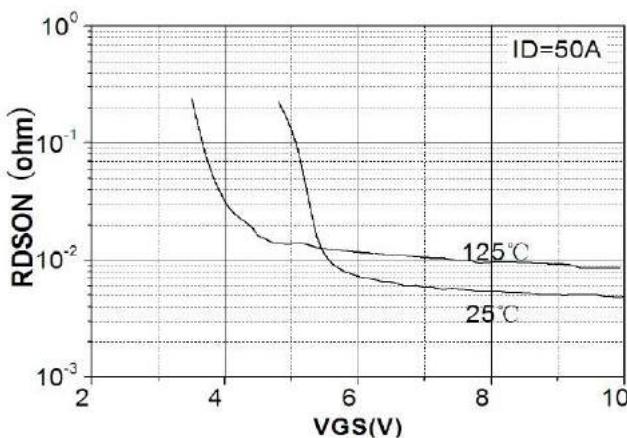
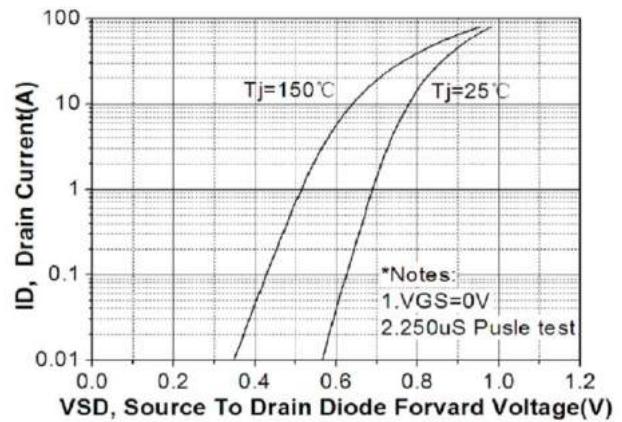
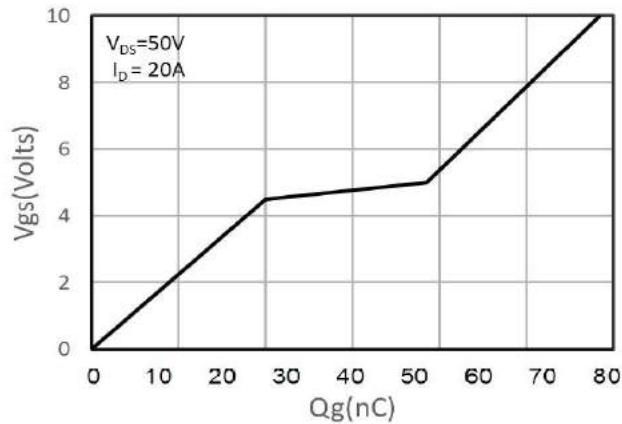
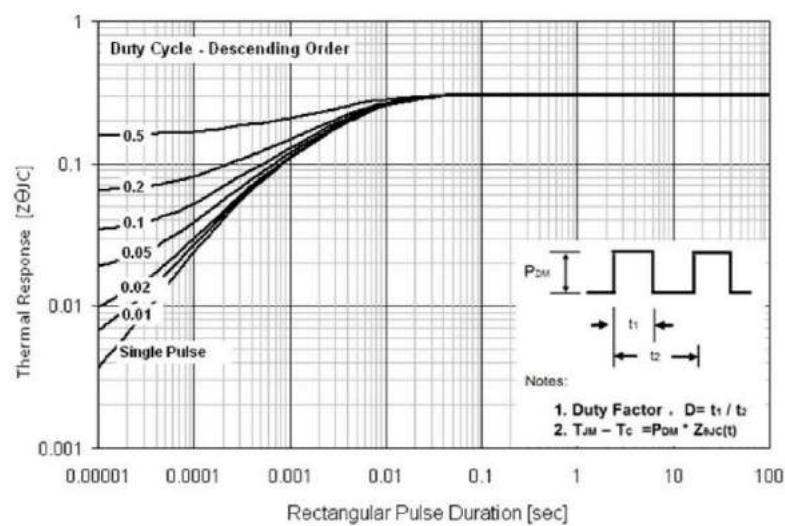
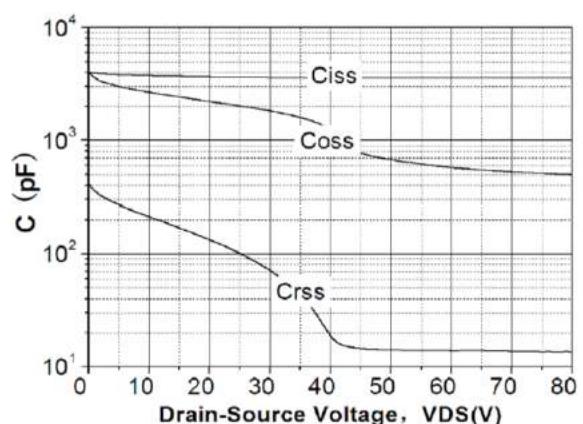
95V N-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

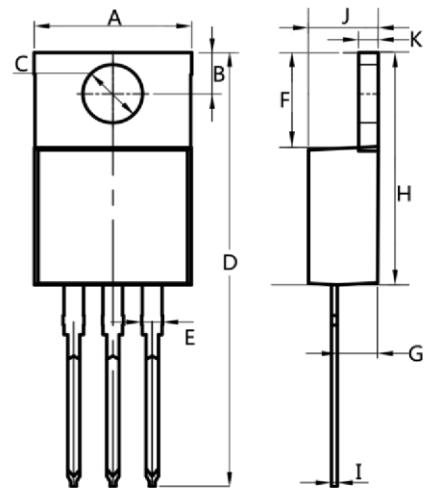
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-source breakdown voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	95	100		V
VGS(th)	Gate threshold voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A} T_J=25^\circ\text{C}$	2.0	3.0	4.0	V
IDSS	Zero gate voltage drain current	$V_{DS}=95\text{V}, V_{GS}=0\text{V} T_J=25^\circ\text{C}$	-		1	μA
IDSS	Zero gate voltage drain current	$V_{DS}=95\text{V}, V_{GS}=0\text{V} T_J=125^\circ\text{C}$		- 5		μA
IGSS	Gate-source leakage current	$V_{GS}=20\text{V}, V_{DS}=0\text{V}$	-	-	100	nA
RDS(on)	Drain-source on-state resistance	$V_{GS}=10\text{V}, I_D=50\text{A}, T_J=25^\circ\text{C}$	-	5.8	7.0	$\text{m}\Omega$
gfs	Transconductance	$V_{DS}=5\text{V}, I_D=50\text{A}$	-	84.2	-	S
Ciss	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=40\text{V}, f=1\text{MHz}$	-	3107	-	pF
Coss	Output Capacitance		-	1060	-	pF
Crss	Reverse Transfer Capacitance	$V_{GS}=10\text{V}, V_{DS}=40\text{V}, I_D=25\text{A}$	-	30	-	pF
QG	Gate Total Charge		-	48.3	-	nC
Qgs	Gate-Source charge		-	14.9	-	nC
Qgd	Gate-Drain charge		-	12.9	-	nC
td(on)	Turn-on delay time	$T_J=25^\circ\text{C}, V_{GS}=10\text{V}, V_{DS}=40\text{V}, R_L=3\Omega$	-	20.1	-	ns
t _r	Rise time		-	38.9	-	ns
td(off)	Turn-off delay time		-	45.1	-	ns
t _f	Fall time		-	22.5	-	ns
R _G	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	-	2	-	Ω
VSD	Body Diode Forward Voltage	$V_{GS}=0\text{V}, I_{SD}=50\text{A}$	-	0.9	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$	-	61	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F=20\text{A}, dI/dt=500\text{A}/\mu\text{s}$	-	560	-	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test cond \equiv 300us duty cycle \leq 2%, duty cycle ition is $V_{DD}=72\text{V}$ $V_{GS}=10\text{V}$, $L=0.1\text{mH}$,
- 4、The power dissipation is limited by 175°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

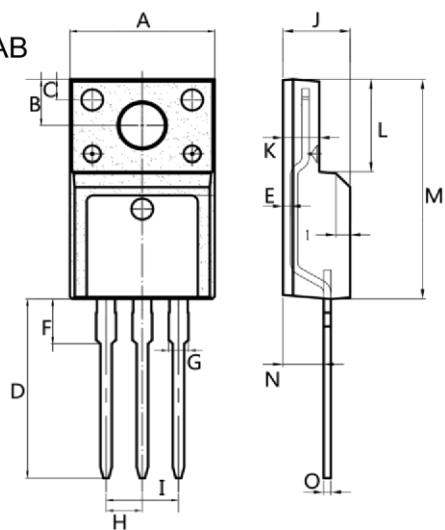
Typical Characteristics

Figure 1. Typ. Output Characteristics ($T_j=25\text{ }^\circ\text{C}$)

Figure 2. Transfer Characteristics

Figure 3. On-Resistance vs. Drain Current and Gate Voltage Figure

Figure 4. On-Resistance vs. Junction Temperature

Figure 5. On-Resistance vs. Gate-Source Voltage

Figure 6 . Body-Diode Characteristics

95V N-Channel Enhancement Mode MOSFET

Figure 7. Gate-Charge Characteristics

Figure 8. Drain Current Derating

Figure 9: Normalized Maximum Transient Thermal Impedance

Figure 10. Capacitance Characteristics

TO-220AB


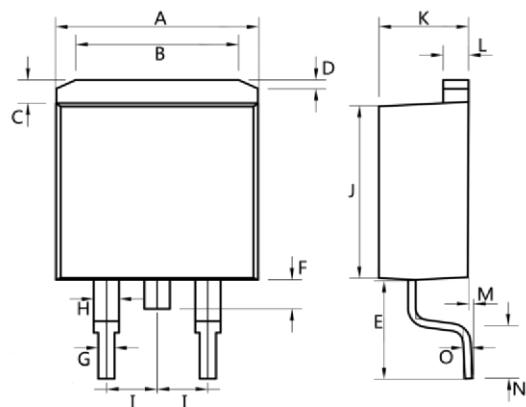
Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter

ITO-220AB


Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ	2.54
I	Typ	5.08
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter

TO-263


Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ	2.54
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter